Exemption Requests Published by the European Commission

Legend:

Adopted (including slightly modified)
Under Consideration
Rejected or Withdrawn
Unknown

Please note that the wording used in the Commission Consultations is often not the same as the wording of the exemptions finally adopted!

Consultation closing 5 July 2004

1. Lead used in compliant-pin VHDM (Very High Density Medium) connector system **(21 October 2005)**
2. Lead as a coating material for a thermal conduction module c-ring **(21 October 2005)**
3. Lead and cadmium in optical and filter glass **(21 October 2005)**
4. Lead in optical transceivers for industrial applications (withdrawn)
5. Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 85% in proportion to the tin-lead content (exemption until 2010) **(21 October 2005)**
6. Lead in high melting temperature type solders (i.e. tin-lead solder alloys containing more than 85% lead) and any lower melting temperature solder required to be used with high melting temperature solder to complete a viable electrical connection **(21 October 2005)**
7. Lead in solders to complete a viable electrical connection internal to certain Integrated Circuit Packages (Flip Chips) (exemption until 2010) **(21 October 2005)**
8. Article 4(1) substances in safety equipment for fire and rescue services.
9. Lead in lead-bronze bearing-shells and bushes **(13 October 2005)**

Consultation closing 11 February 2005

1. Lead in tin whisker resistant coatings for fine pitch applications
2. Lead bound in glass, crystal glass, lead crystal or full lead crystal in general **(12 October 2006)**
3. Chromium (also in oxidation state (VI)) and Cadmium as colouring batch addition each form up to a content of 2 % in glass, crystal glass, lead crystal

or full lead crystal used as decorative and / or functional part of electric or electronic equipment,

4. Solders containing lead and/or cadmium for specific applications, **(12 October 2006)**
5. Hexavalent chromium (CRVI) passivation coatings, **(12 October 2006)**
6. Lead in lead oxide glass plasma display panels, **(21 April 2006)**
7. Lead in connectors, flexible printed circuits, flexible flat cables (withdrawn),
8. Lead oxide in lead glass, bonding materials of magnetic heads and magnetic heads,
9. Cadmium as doping material in avalanche photodiodes (APDs) for the optical fiber communication systems,
10. Lead in optical isolators, **(12 October 2006)**
11. Lead in sheath heater of Microwaves,
12. Cadmium pigments except for applications banned under Directive 91/338/EEC amending Directive 76/769/EEC relating to the restriction on the marketing and use of certain substances,
13. High Intensity Discharge (HID) lamps for professional U.V. applications, containing lead halide as radiant agent (Lead halide as radiant agent in High Density Discharge (HID) lamps used for professional reprography applications.) **(21 April 2006)**
14. Discharge lamps for special purposes containing lead as activator in the fluorescent powder (1% lead by weight or less) (Lead as activator in the fluorescent powder (1% lead by weight or less) of discharge lamps when used as tanning lamps containing phosphors such as BSP (BaSi2O5:Pb) as well as when used as speciality lamps for diazo-printing reprography, lithography, insect traps, photochemical and curing processes containing phosphors such as SMS ((Sr,Ba)2MgSi2O7:Pb).), **(21 April 2006)**
15. Discharge lamps containing lead in the form of an amalgam (Lead with PbBiSn-Hg and PbInSn-Hg in specific compositions as main amalgam and with PbSn-Hg as auxiliary amalgam in very compact Energy Saving Lamps (ESL).) **(21 April 2006)**
16. Mercury free flat panel lamp,
17. Special purposes Black Light Blue (BLB) lamps, containing lead in the glass envelope, **(12 October 2006)**
18. Low melting point alloys containing lead,
19. Galvanised steel containing up to 0.35% lead by weight and aluminium with an unintended lead content up to 0.4% lead by weight in electrical and electronic equipment,
20. Lead in solder and hexavalent chromium in surface treatment, in parts recovered from production printers and copying equipment, sold, rented or leased or otherwise returned from professional users other than private households, originally put on the market before 1 July 2006, and reused for the same purpose within the original manufacturer's closed loop system until 1 July 2011. In this context a closed loop system means a system whereby the equipment remains the property of the manufacturer or is subject to

Comment [CS1]: This exemption request was split into three parts, one of which was adopted as exemption 24 ("Lead in solders for the soldering to machined through hole discoidal and planar array ceramic multilayer capacitors.")

Comment [CS2]: This exemption request was granted (exemption 22, "Lead as impurity in RIG (rare earth iron garnet) Faraday rotators used for fibre optic communications systems"), but is under review in the latest Commission consultation.

other contractual arrangements and is returned to the manufacturer either when the contract expires or at end of life,

21. Cadmium sulphide photocells,
22. Applications of lead, mercury, cadmium, hexavalent chromium, PBBs and PBDEs in electrical and electronic equipment in the aeronautic and aerospace sectors that requires high safety standards.

Consultation closing 28 October 2005

1. Linear incandescent lamp (Lead in linear incandescent lamps with silicate coated tubes.); **(21 April 2006)**
2. Mercury in switches;
3. Special ICs having tin-lead solder plating on leads used in professional equipment;
4. Specific modular units including tin-lead solder being used in special professional equipment;
5. Solders containing lead and /or cadmium for specific applications where local temperature is higher than 150 deg C and which need to work properly more than 500 hours;
6. Lead in solder for printed circuit boards for emergency lighting products;
7. Hexavalent chromium (Cr-VI) in chromate conversion coatings as surface treatment;
8. Lead in gas sensors;
9. Concerning of PbO (Lead in Seal Frit) used for making BLU (Back Light Unit) Lamps; **(12 October 2006)**
10. Cadmium in opto-electronic components;
11. Non-consumer mechanical power transmission systems including speed reducers and mechanical couplings which rely on electrical/electronic components for safe control and operation;
12. Electrical and electronic components contained in heating ventilating and air conditioning building systems, commercial refrigeration systems and transport refrigeration systems;
13. Cadmium-bearing copper alloys;
14. Electrical/electronic components contained mobile and stationary air compressors and vacuum systems, compressed air contaminant removal systems and pneumatic contractor's air tools;
15. Electrical/electronic equipmentthat are: used in transport -aviation, aerospace, road, maritime, rail; installed in to the fabric of buildings – elevators, escalators, moving walks, dumb waiters, and heating, cooling and ventilation systems, and fire and security systems; used in the energy generation and transmission; used in mining and mineral processing; used for non-consumer mechanical power transmission systems; industrial process pumps and compressors; used in industrial refrigeration; and used in military applications;

Comment [CS3]: This type of equipment is not covered by RoHS (Category 9, monitoring and control instruments)

16. Lead alloys as electrical/mechanical solder for transducers used in high-powered professional and commercial loudspeakers; **(12 October 2006)**
17. Cadmium oxide;
18. Solder tin of the thermo fuse with a defined low melting point;
19. Lead in lead oxide glass used in plasma display panel (PDP); **(12 October 2006)**
20. Lead in solder on small PCB and tinned legs of primary components;
21. Use of the not lead free component NEC V25 in the Memor 2000;
22. Lead used in shielding of radiation for Non Medical X-ray equipment
23. Lead based solders sealed or captured within heat-shrinkable components and devices.

Consultation closing 10 February 2006

1. On-Semi MCR265-10 SCR;
2. Components NEC V55;
3. The use of lead in solder applications for electronic components of musical instruments having an average lifespan in excess of 10 years;
4. Lead solder alloy in Surge protective devices (SPDs);
5. Inventory of Special ICs having tin-lead solder on/in leads/balls, used in specialist/professional equipment;
6. Lead alloys as electrical/mechanical solder for transducers used in high-powered professional and commercial loudspeakers; **(12 October 2006)**
7. Solder containing lead for applications where the local temperature exceeds 150 C and reliable operation for a minimum of 30,000 hours is required;
8. T in-lead solder in the manufacture of professional audio equipment;
9. Specific modular units including tin-lead solder being used in special professional equipment;
10. Lead in electronic vacuum tubes;
11. Lead in aluminium used in gas valves for domestic cooking appliances;
12. "8. Cadmium and its compounds in electrical contacts except for applications of one-shot operation function such as thermal links and cadmium plating except for the applications banned under Directive 91/338/EEC amending Directive 76/769/EEC relating to the restriction on the marketing and use of certain dangerous substances and preparations.";
13. Lead in solder of parts recovered from gaming/amusement machines put on the market before 1/07/06 and reused for the same purpose within a manufacturer's closed loop until July 2014;
14. Lead in solders in components and assemblies used in non-consumer products, provided that: - such components and assemblies were purchased or are subject to a proven last-time buy contract placed before 1 July, 2006; and - such components and assemblies are used in models of EEE that were already available on the market before 1 July 2006;
15. "8. Cadmium plating as defined in Directive 91/338/EEC except for applications banned under Directive 91/338/EEC amending Directive

Comment [cs4]: Actual text adopted: "Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC (*) amending Directive 76/769/EEC (**) relating to restrictions on the marketing and use of certain dangerous substances and preparations. "

76/769/EEC relating to restrictions on the marketing and use of certain dangerous substances and preparations."

Comment [cs5]: See comment above – two requests combined into one exemption.

Consultation closing on 15 May 2006

1. Cadmium and cadmium oxide in thick film pastes used on beryllium oxide substrates until January 1, 2008;
2. Gaskets of butyl rubber material vulcanised with chinondioxim and lead tetraoxide, for use in Aluminium Electrolytic Capacitors;
3. Sharp LQ104X2LX11 (formerly Fujitsu FLC26XGC6R-01);
4. Quartz Crystal Resonator and in Fine Pitch Electronics Systems used in the Swiss Watch Industry;
5. Cadmium in opto- electronic components;
6. Transducers used in professional loudspeaker systems, using tin-lead solder;
7. Tin-lead solder in the manufacture of professional audio equipment;
8. Components used in the manufacture of the Hog1000, Hog500, Event416, Event408, ESP2-24 and ESP2-48 lighting control consoles;
9. Specific modular units, including tin-lead solder, being used in special professional equipment;
10. Inventory of special ICS having tin-lead solder on/in leads/balls, used in specialist/professional equipment;
11. Cadmium Mercury Telluride;
12. Lead contained in Babbit lined bearings;
13. Cadmium alloys as electrical/mechanical solder joints to electrical conductors located directly on the voice coil in transducers used in high-powered loudspeakers;
14. Thermal cutoff with a fusible element that contains lead (and possibly cadmium, mercury and hexavalent chromium) for applications where normal operating temperature exceeds 140 C and reliable, predictable, operation for a minimum of 30,000 hours is required;
15. Mercury free flat panel lamp;
16. Electronic equipment where the reliability, durability and longevity of the equipment is paramount;
17. Semi Red Brass C84400, 81-3-7-9 or a similar Brass material. Used on radio frequency line sections;
18. Lead is used as an alloy to the copper in 6 to 8 % by weight. Needed for casting and machinability characteristics;
19. Lead in solders for electronic equipments used for the monitoring, the protection and the safety of people in healthcare, telecare and emergency calls domains in professional and private sectors;
20. FPGA devices manufactured by Xilinx (XC5202-6VQ100C, XC4003E-3VQ100C and XC4013E-3PQ240C) containing lead solder (Pb) used in the plating of the device terminations;

Comment [CS6]: This exemption request is being considered under the consultation closing in January 2007.

Comment [cs7]: Actual text adopted: "Lead in soldering materials in mercury free flat fluorescent lamps (which e.g. are used for liquid crystal displays, design or industrial lighting). "

21. Lead oxide in seal frit used for making window assemblies for argon and krypton laser tubes;
22. Smart card readers (product: GemSelf700-MS2, GCR700-3ZS, Vodafone D2 , GCR760 and GemSelf750 SV);
23. Use of mercury in Babcock's DC plasma displays and use of Lead Oxide (PbO) in Babcock's DC plasma displays frit seal.

Comment [cs8]: Actual text adopted: " Lead oxide in seal frit used for making window assemblies for Argon and Krypton laser tubes."

Consultation closing on 10 January 2007

1. Lead used for shielding of x-radiation emissions for CRT;
2. Lead as soldering alloy in high performance communication electronic board and hexavalent chromium (Cr-VI);
3. GemCore 410 EMV;
4. SAVBIT solder;
5. Sn-Pb soldering used in Ground-based Aeronautical Communication Equipment Manufacturing;
6. Transducers used in professional loudspeaker systems, using tin-lead solder;
7. Tin-lead solder in the manufacture of professional audio equipment;
8. Inventory of special ICS having tin-lead solder on/in leads/balls, used in specialist/professional equipment;
9. Crystal Stones within the battery operated watch;
10. EEE used for the broadcast and homeland security sector;
11. AM186ES-V40 containing lead in used in the leads over plating and AM79C961AKC containing lead in used in the leads over plating;
12. Cadmium sulphide or cadmium selenide in polymer based thin film transistor;
13. Lead used in the soldering for surface finishing at the electric pole terminal on the electronic parts;
14. Cadmium contained in the cadmium oxide of a thick film ceramic substrate;
15. All electronics assemblies using lead in solder;
16. Lead in electric overblankets for Hot Spot detection;
17. MPC10 used in automatic vending machines to achieve the payment by card;
18. Hexavalent Chrome Cr-VI when used as a passivate;
19. Lead contained in circuit boards, obsolete and non-compliant Intel 80c188/86 EA\XL microprocessors, Analog Devices ADMC300 DSP, and NEC uPD7101 DART and hexavalent chromium;
20. Component used in the manufacture of electric blankets and heating pads.
21. Request to delete exemption for "Lead as impurity in RIG (rare earth iron garnet) Faraday rotators used for fibre optic communications systems."
22. Lead in Trimmer Potentiometer elements.
23. Cadmium in opto-electronic components.

Comment [cs9]: Likely to be finally adopted in April or May 2009. Actual text: "Lead in solders for the soldering of thin copper wires of 100 µm diameter and less in power transformers."

Comment [cs10]: Was recommended for adoption (but never adopted) with 2008 end date – now obsolete.

Comment [cs11]: Was recommended for adoption (but never adopted) with 2008 end date – now obsolete.

Comment [cs12]: Likely to be finally adopted in April or May 2009, taking effect Jan 1, 2010.

Comment [cs13]: Likely to be finally adopted in April or May 2009.

Consultation closing on 10 August 2007

1. Lead in silver rings on the exterior lamp surface of induction-type fluorescent lamps;
2. Mercury in plasma displays;
3. Cadmium in Photocells for accurate control of lighting equipment;
4. Cadmium-based photo-resistors used in professional audio equipment;
5. RELOCK FUSE, Model X-09;
6. High voltage diodes in glass housings;
7. Cadmium and cadmium oxide in thick film pastes used on beryllium oxide substrates.

Consultation closing on 10 April 2008

1. Lead in solders for the connection of very thin enamelled wires with a terminal.
2. Lead and Cadmium as components of the glazes and colour used to glaze or decorate lamp bases, lamp carriers or clocks.
3. Lead in solders in a third party component of Cortex family equipment.

Consultation closing on 31 July 2008

4. Cadmium For Use In Solid-State Illumination & Display Systems

Consultation closing on 8 October 2008

5. Lead in solders for the connection of very thin (<100 µm) enamelled copper wires and for the connection of enameled copper clad aluminium wires with a copper layer smaller than 20 µm

Comment [cs14]: This is essentially a request for amendment of exemption 21. It will be examined under the review of existing exemptions.

Comment [cs15]: Likely to be finally adopted in April or May 2009. Actual text: “Mercury used as a cathode sputtering inhibitor in DC plasma displays with a content up to 30 mg per display until 1 July 2010.”

Comment [cs16]: Likely to be finally adopted in April or May 2009. Actual text: “Cadmium in photoresistors for optocouplers applied in professional audio equipment until 31 December 2009.”

Comment [cs17]: The application was considered out of the scope of the RoHS Directive.

Comment [cs18]: Likely to be finally adopted in April or May 2009. Actual text: “Lead in the plating layer of high voltage diodes on the basis of a zinc borat glass body.”

Comment [cs19]: Likely to be finally adopted in April or May 2009. Actual text: “Cadmium and cadmium oxide in thick film pastes used on aluminium bonded beryllium oxide."

Comment [cs20]: All 5 of these requests are under consideration as new exemptions. However, procedurally they have been wrapped up in the review of existing exemptions.